

**TITLE OF INVENTION: POLISHING PAD, METHOD FOR
MANUFACTURING THE SAME, AND METHOD FOR MANUFACTURING
SEMICONDUCTOR DEVICE USING THE SAME**

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ABSTRACT

A polishing pad includes a polishing layer, wherein the polishing layer includes zinc (Zn), and a concentration of the zinc (Zn) is 0.5 ppm to 40 ppm parts by weight based on the total weight of the polishing layer. In an exemplary embodiment, a polishing pad is provided wherein a concentration of the zinc (Zn) is 0.5 ppm to 40 ppm parts by weight based on the total weight of the polishing layer, a concentration of the iron (Fe) is 1 ppm to 50 ppm parts by weight based on the total weight of the polishing layer, and a concentration of the aluminum (Al) is 2 ppm to 50 ppm parts by weight based on the total weight of the polishing layer. The polishing pad exhibits physical properties corresponding to the metal concentration, and thus, a polishing rate and defect prevention performance within a target range may be implemented in polishing an object to be polished.

[Figure. 1]